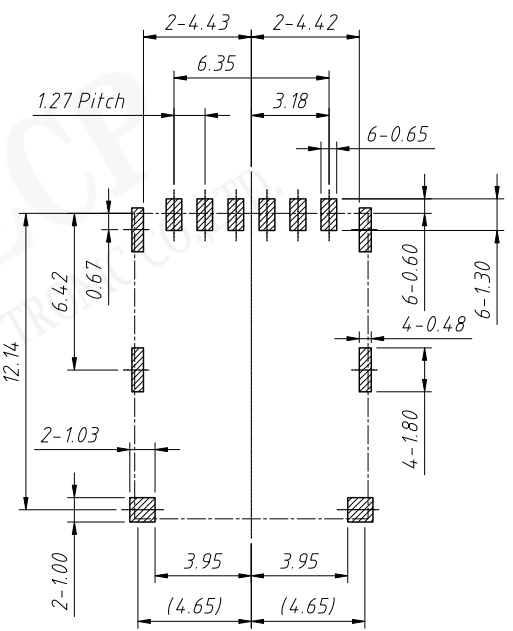
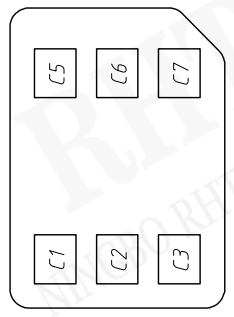


@All Solder-Tail  
Terminal Solder pin Flatness 0.08 Max.  
Shell Solder pin Flatness 0.10 Max.



Recommended PCB Layout  
Tolerance (Top View) ±0.05



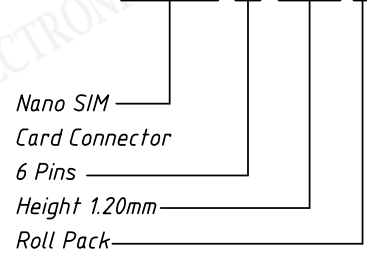
Nano SIM Card Pad

**Material:**  
Housing: High Temp. Thermoplastic, UL 94V-0, Black  
Contact: Copper Alloy 0.10T, Gold Flash On Contact Area and Solder Area 50U" Min Nickel Under-Plated  
Shell: Stainless Steel 0.10T, Nickel Plating Over ALL

**Electrical:**  
Current Rating: 1A  
Contact Resistance: 100mΩ Max.  
Insulation Resistance: 500MΩ Min  
Dielectric Withstanding Voltage: 500V R.M.S. Min  
Life Test: 1500 Cycles  
@ Represent Critical Dimensions

**Order Information:**

RE-C-SIM-D01-6P-H1.20-R



UNITS:mm	SHEET SIZE:A4		SCALE:---
>0~3	>3~18	>18~50	>50~120
±0.12	±0.15	±0.3	±0.5